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ABSTRACT OF THE DISCLOSURE

The present invention discloses a semiconductor package for enhancing heat dissipation. Only an upper mold of the semiconductor package is encapsulated, and a heat sink having a thickness variable with demands is mounted to a die pad and a part of a plurality of leads with thermally conductive and electrically insulating adhesive glue. As the thickness of the heat sink is adjustable according to user's demands, the present invention is more suitable for manufacturing thin products. The width of the heat sink covers the die pad and a part of the plurality of leads. Therefore, the heat generated by the die could be not only dissipated to the atmosphere through the leadframe, but also dissipated through a printed circuit board connected to the leads of the leadframe.

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